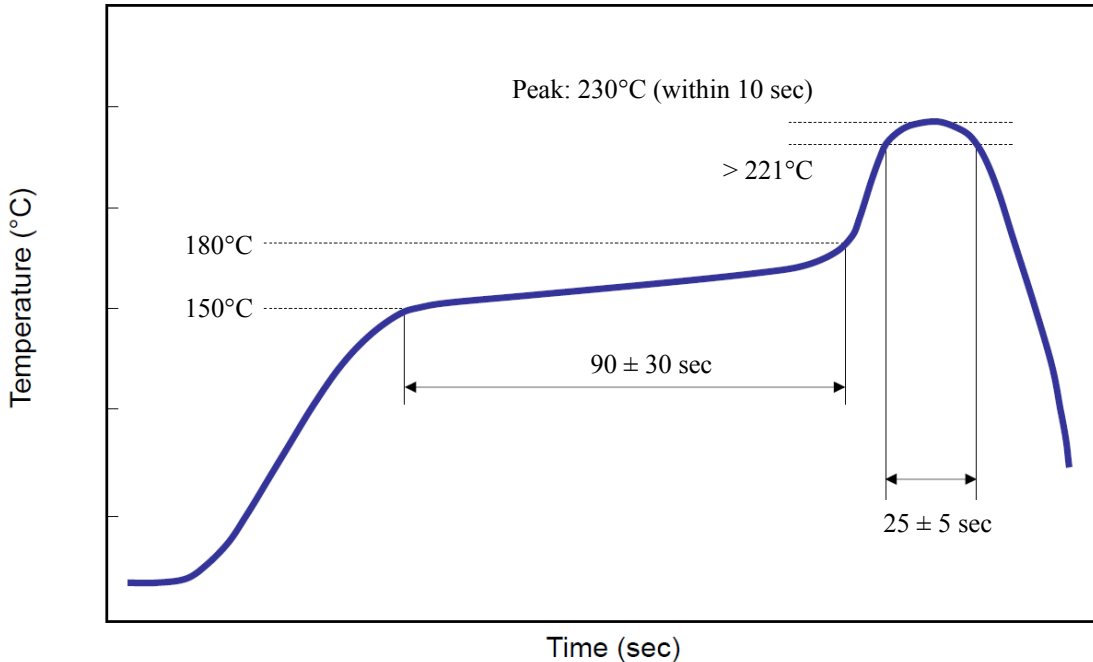


Suggested Reflow Profile



Notes

1. Avoid touching any solderable surfaces or contaminating surfaces to assure solderability.
2. Avoid forcing the filter into place.
3. Units may be cleaned via solvent based, aqueous, semi-aqueous, and alcohol based systems. Be sure to completely dry the units as any entrapped moisture will affect the electrical performance. If an aqueous wash is used, a bake may be required.
4. A typical reflow profile is provided above. The actual profile is not as important as ensuring a defect free process. The most important parameter is to not exceed the peak temperature to prevent internal reflow.
5. The units are assembled using SN95SB5 high temperature solder. KR Electronics recommends that customers use a SAC solder with a melting point of 217°C or an equivalent during installation for signal and ground connections.
6. Control the rate of heating and cooling to prevent thermal cracking of the devices. Heating or cooling, should not exceed a rate of 200°C per minute. Spikes must not exceed 100°C maximum for any operation. Avoid forced cooling or contact with heat sinks, such as conveyor belts, metal tables or cleaning solutions, before the units reach room temperatures.